

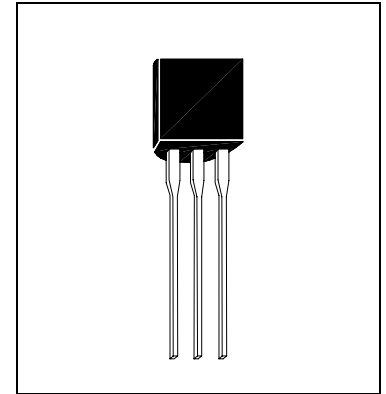


HMPS6562

PNP SILICON TRANSISTOR

Description

The HMPS6562 is designed for audio transistor.



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -50 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage -25 V
 VCEO Collector to Emitter Voltage -25 V
 VEBO Emitter to Base Voltage -5 V
 IC Collector Current -500 mA

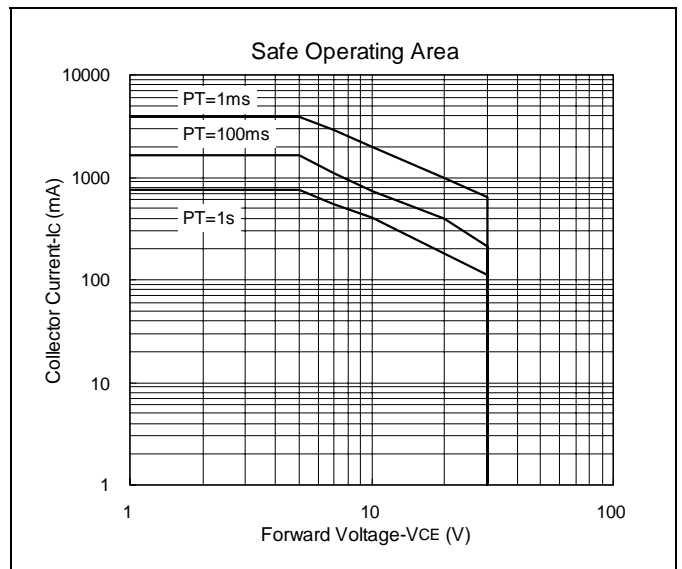
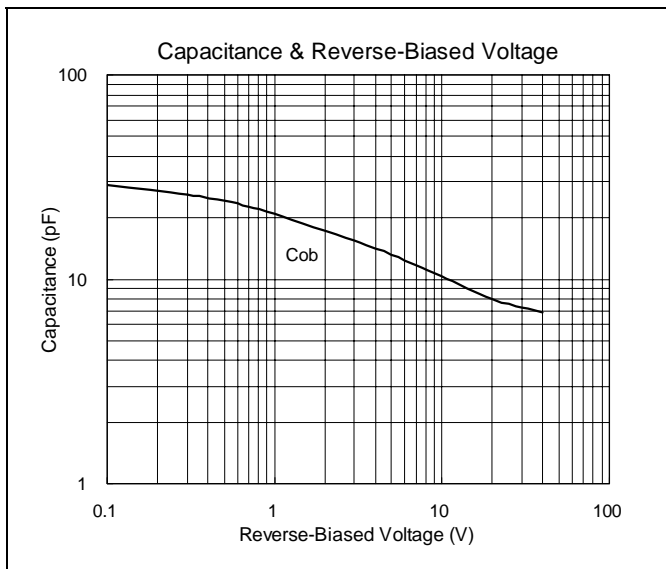
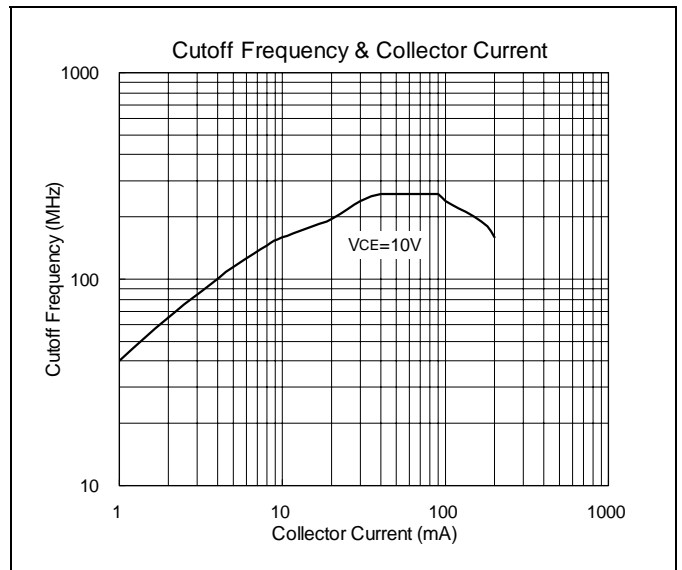
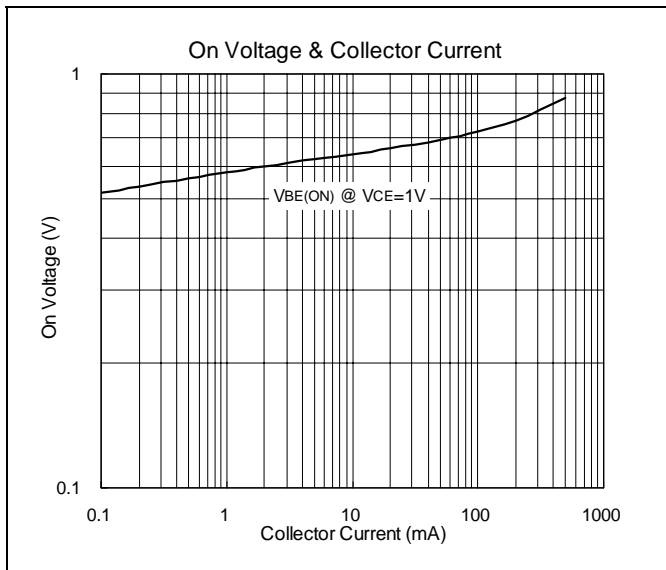
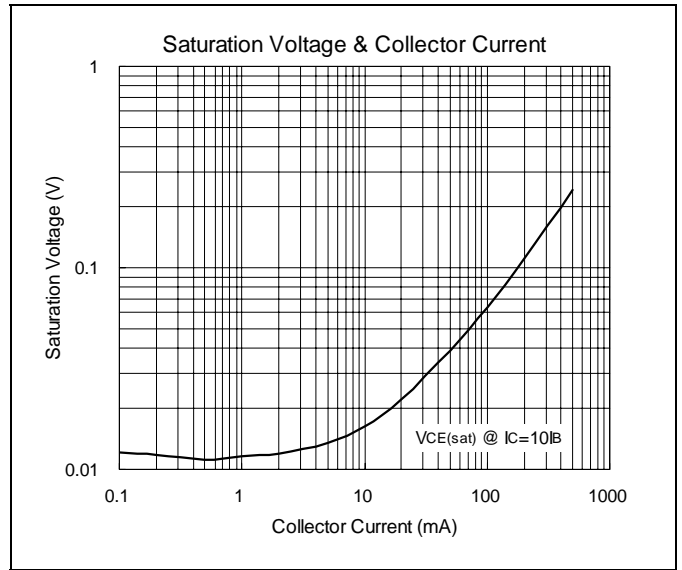
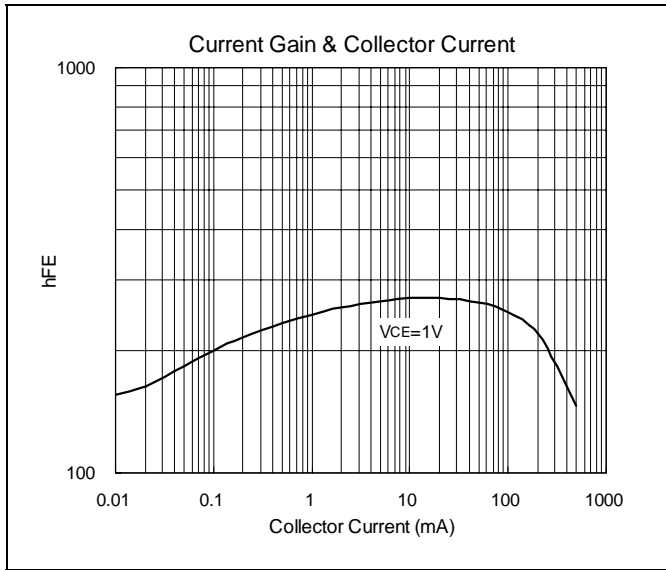
Characteristics (Ta=25°C)

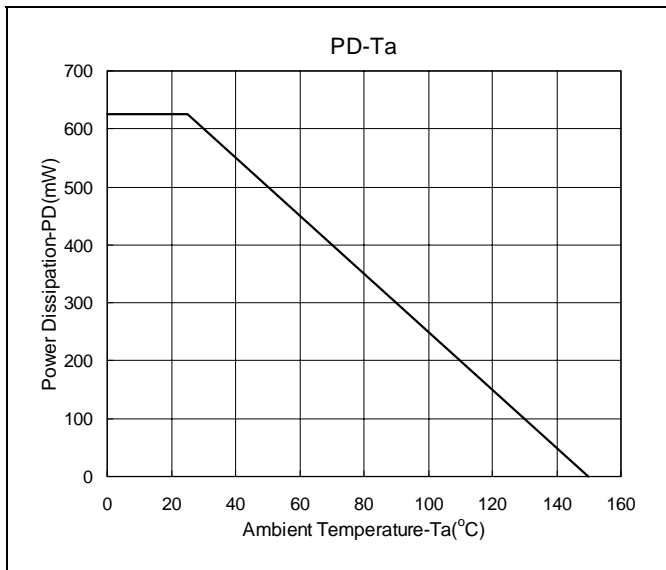
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-25	-	-	V	IC=-100uA, IE=0
BVCEO	-25	-	-	V	IC=-10mA, IB=0
BVEBO	-5	-	-	V	IE=-100uA, IC=0
ICBO	-	-	-100	nA	VCB=-20V, IE=0
ICEO	-	-	-100	nA	VCE=-25V, IB=0
IEBO	-	-	-100	nA	VEB=-4V, IC=0
*VCE(sat)	-	-	-0.5	V	IC=-500mA, IB=-50mA
VBE(on)	-	-	-1.2	V	VCE=-1V, IC=-500mA
*hFE1	35	-	-		VCE=-1V, IC=-10mA
*hFE2	50	-	-		VCE=-1V, IC=-100mA
*hFE3	50	-	200		VCE=-1V, IC=-500mA
fT	60	-		MHz	VCE=-10V, IC=-10mA, f=30MHz
Cob	-	-	30	pF	VCE=-10V, f=100KHz, IE=0

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



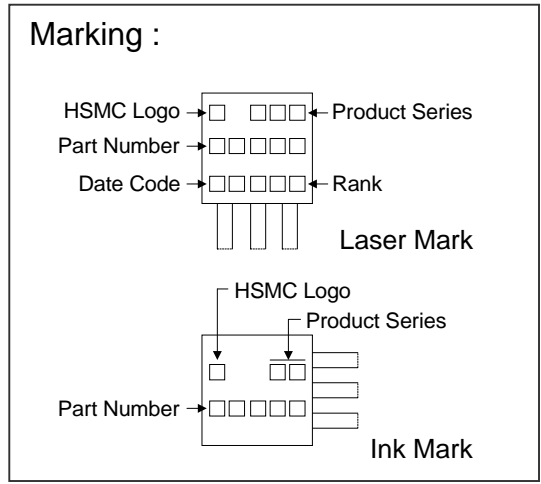
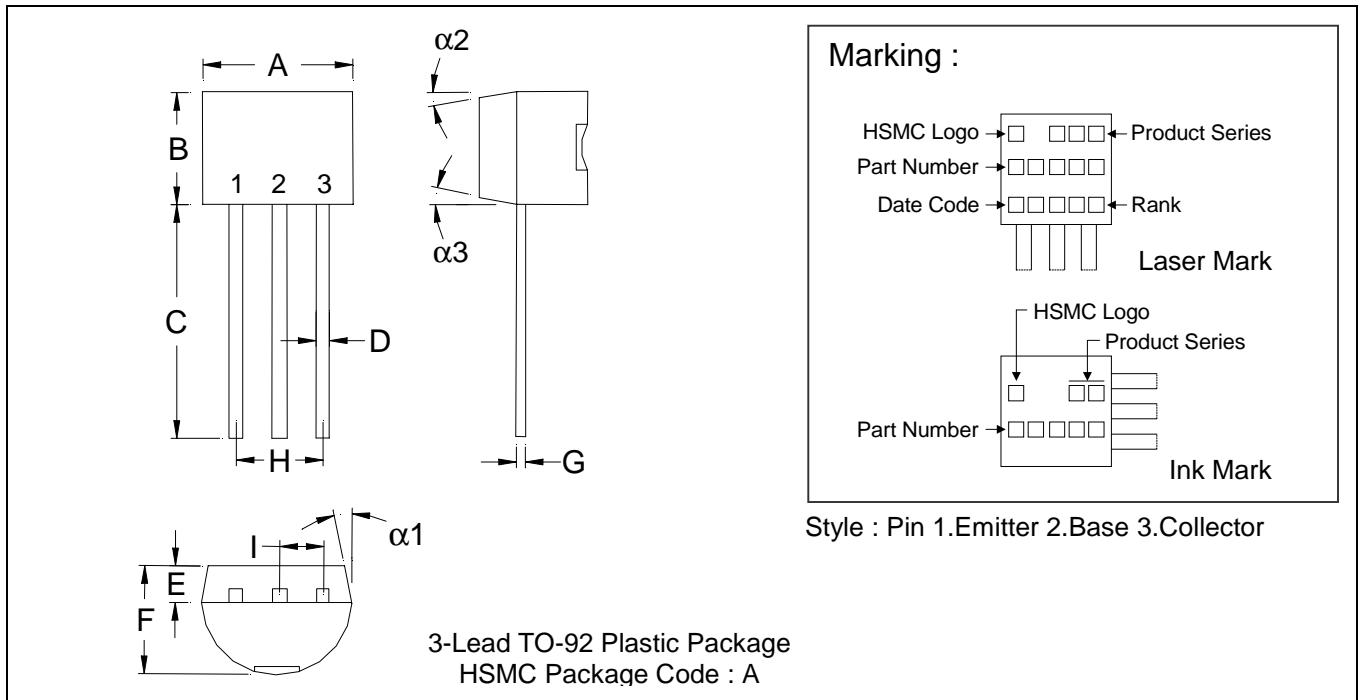
Characteristics Curve







TO-92 Dimension



Style : Pin 1. Emitter 2. Base 3. Collector

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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